

Product Data Sheet

MTCA Power Backplane,
Part No. 502-50096-183

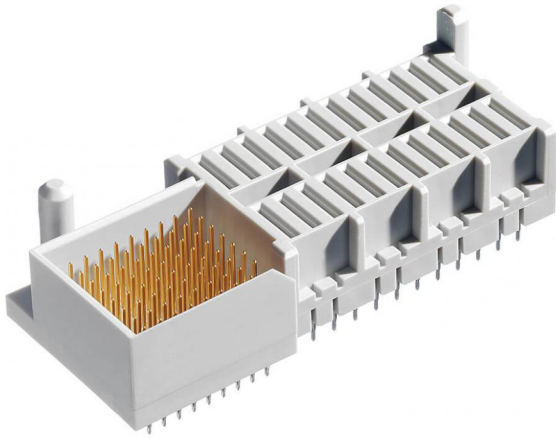


Illustration similar



Perpendicular



Press-fit



Power



Rugged

- contacts: 72 signal, 24 power
- Press-fit
- according to PICMG specifications



» to product on www.ept.de



» to product group Micro TCA

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Technical Specifications

Basics

Specification	PICMG® MTCA.0 R1.0
No. of Contacts	96 (24 Power, 72 Signal)
Termination Technology	Press-fit
Termination Length	3.7 mm
Operating Temperature Range	-55°C to +105°C

Material

Insulator Material	PBT glass filled, UL 94 V-0
Contact Material	Copper alloy

Mechanical

Mating Force	max. 50 N
Separating Force	max. 50 N
Durability	200 mating cycles

Electrical

Operational Current	Power contacts: max. 12 A, Signal contacts: max. 1 A
Insulation Resistance	$\geq 10^8 \Omega$
Test Voltage	80 V r.m.s.

Approval / Compliance

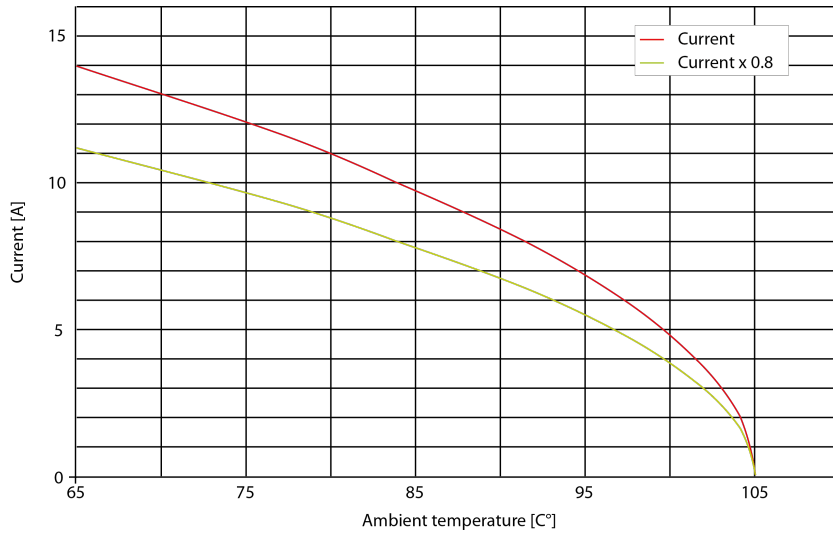
UL file	E130314
Environment	RoHS compliant

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Derating Diagram



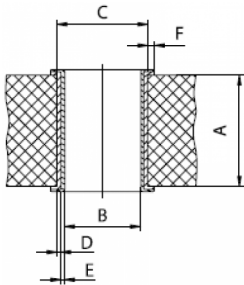
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Hole Specifications

Plated through-hole according to IEC 60352-5



Material	imm. Sn printed circuit boards
Nominal Hole	Ø 0.6 mm
A PCB Thickness	min 1.44 mm
B Plated Hole	Ø 0.60 ±0.05 mm
C Drill Hole	0.70 ±0.02 mm
D Cu Plating	min. 25 µm
E Surface	max. 1.5 µm; imm. Sn plating
F Annular Ring	min. 0.1 mm

Material	Ni, Au printed circuit boards
Nominal Hole	Ø 0.6 mm
A PCB Thickness	min 1.44 mm
B Plated Hole	Ø 0.60 ±0.05 mm
C Drill Hole	0.70 ±0.02 mm
D Cu Plating	min. 25 µm
E Surface	Ni, Au plating, 0.05 - 0.2 µm Au over 2.5 - 5 µm Ni
F Annular Ring	min. 0.1 mm

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Drawings

Component data in 2D and 3D format you can download here:

[» PDF](#)

[» 3D IGES](#)

[» 3D STEP](#)

[» 3D PDF](#)